

L Number	Hits	Search Text	DB	Time stamp
2	13	charged adj particle and ( inspection near2 hole?)	USPAT; US-PGPUB; EPO; JPO	2003/04/08 11:12
1	19	Electron adj beam and ( inspection near2 hole?)	USPAT; US-PGPUB; EPO; JPO	2003/04/08 11:23
3	29562	Inspection and ( hole? near2 wafer or substrate or mask? )	USPAT; US-PGPUB; EPO; JPO	2003/04/08 11:26
4	2628	((Inspection and ( hole? near2 wafer or substrate or mask? )) and ( electron near2 beam )	USPAT; US-PGPUB; EPO; JPO	2003/04/08 11:26
5	113	((Inspection and ( hole? near2 wafer or substrate or mask? )) and ( charged adj particle? near2 beam )	USPAT; US-PGPUB; EPO; JPO	2003/04/08 11:27
6	278	((Inspection and ( hole? near2 wafer or substrate or mask? )) and ( electron near2 beam )) and ( current near4 flow\$3 )	USPAT; US-PGPUB; EPO; JPO	2003/04/08 11:31
7	7	((((Inspection and ( hole? near2 wafer or substrate or mask? )) and ( electron near2 beam )) and ( current near4 flow\$3 )) and ( etch\$4 near2 layer? )	USPAT; US-PGPUB; EPO; JPO	2003/04/08 11:28
8	23	((Inspection and ( hole? near2 wafer or substrate or mask? )) and ( charged adj particle? near2 beam )) and ( current near4 flow\$3 )	USPAT; US-PGPUB; EPO; JPO	2003/04/08 11:49
9	7640	((250/307,310,311,396R,396ML,397,440.11,442	USPATCLS. US-PGPUB; EPO; JPO	2003/04/08 11:51
10	4	((250/307,310,311,396R,396ML,397,440.11,442 and ( charged adj particle? near2 inspection )	USPATCLS.) US-PGPUB; EPO; JPO	2003/04/08 11:55
11	17	((250/307,310,311,396R,396ML,397,440.11,442 and ( inspect\$4 near2 hole? )	USPATCLS.) US-PGPUB; EPO; JPO	2003/04/08 13:46
12	644	((250/307,310,311,396R,396ML,397,440.11,442 and ( current near2 flow\$3 )	USPATCLS.) US-PGPUB; EPO; JPO	2003/04/08 13:47
14	4	((250/307,310,311,396R,396ML,397,440.11,442 and ( etch near2 layer? )	USPATCLS.) US-PGPUB; EPO; JPO	2003/04/08 13:49
13	32	((250/307,310,311,396R,396ML,397,440.11,442 and ( substrate near2 current )	USPATCLS.) US-PGPUB; EPO; JPO	2003/04/08 13:50

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